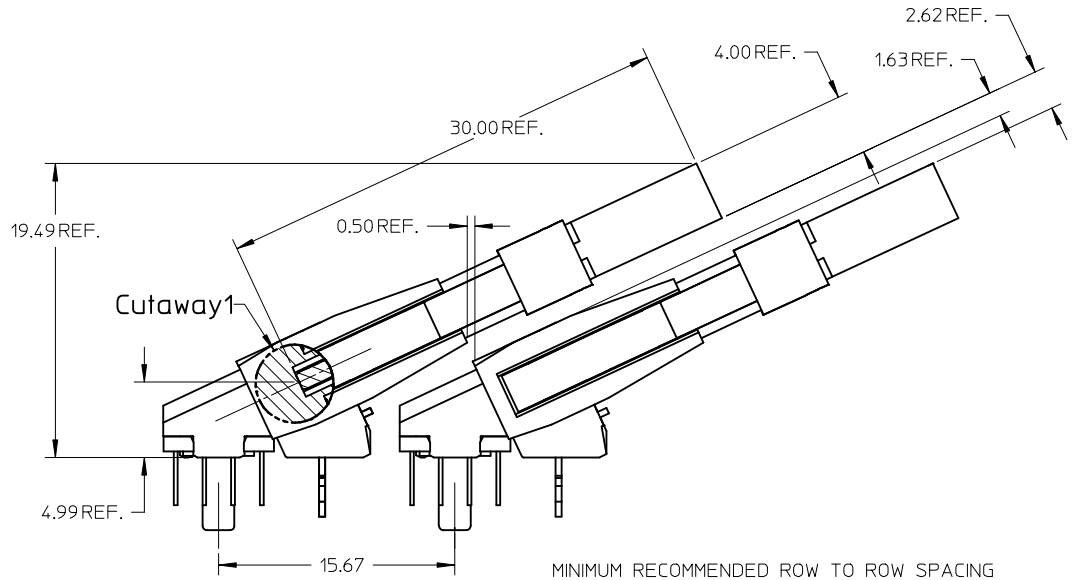
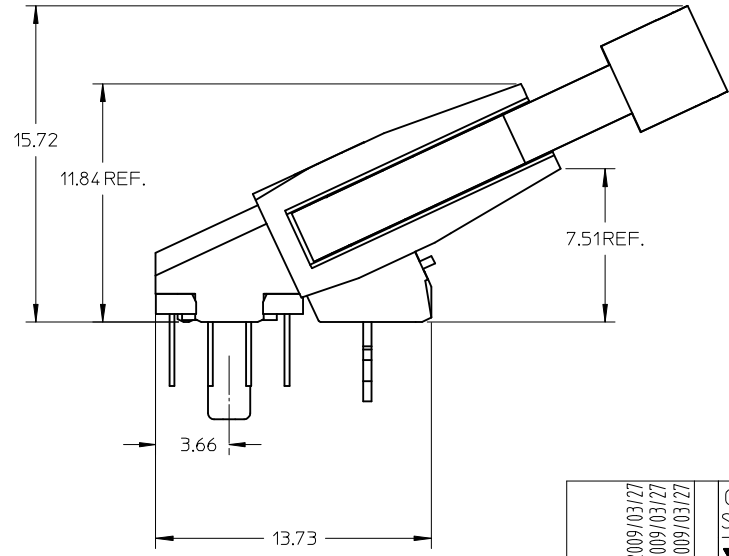


- NOTES:
- MATERIALS : HOUSING AND BASEPLATE
 - LCP, GLASS FILLED, UL 94V-0, BLACK LATCH
 - HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
 - TERMINALS AND FORKLICK - COPPER ALLOY
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
 - REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
 - CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
 - RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 - PRODUCT IS PACKED IN TRAY.
 - MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
 - CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

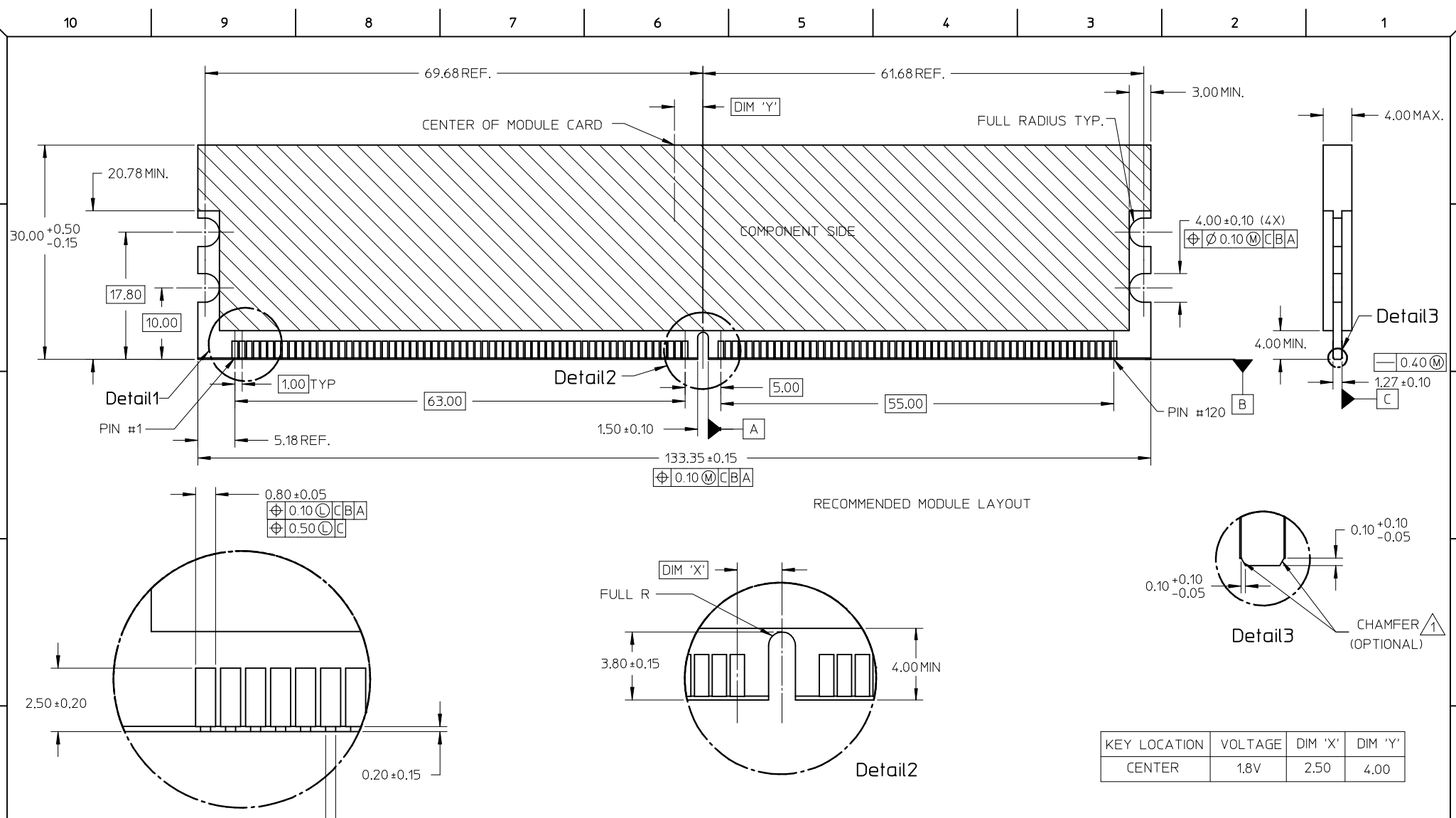
ADDED OPTION EC NO: S2009-0629 DRW:ACCTEH 2009/03/27 CHKD:CGTAN 2009/03/27 APPR:SHLENI 2009/03/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
		mm	INCH	DRAWN BY	DATE	TITLE		
		4 PLACES ± ---	± ---	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
		3 PLACES ± ---	± ---	CHECKED BY	DATE			
		2 PLACES ± 0.25	± ---	SRRAMESH	2004/03/26			
		1 PLACE ± ---	± ---	APPROVED BY	DATE			
		ANGULAR ± 5 °		GGLEE	2004/03/26	MOLEX MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.			
				SEE TABLE	SD-87803-010			
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
		A3	SHEET NO. 1 OF 5					



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)



ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH 2009/03/27 CH'KD: GGTAN 2009/03/27 APPR: SHLENI 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS, 25 DEG.			
	2 PLACES	± 0.25	± ---	SRRAMESH	2004/03/26	MOLEX INCORPORATED				
	1 PLACE	± ---	± ---	APPROVED BY	DATE					
	ANGULAR ± 5 °		GGLLEE		2004/03/26	MATERIAL NO.		DOCUMENT NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87803-010		SHEET NO.			
B1			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

NOTES :
 1 MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

ADDED OPTION
 EC NO: S2009-0629
 DRW:NCCTEH
 CHKD:CGTAN
 APPR:SHLENI

REV	DESCRIPTION
B1	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
▽=0	4 PLACES ±---	±---
∇=0	3 PLACES ±---	±---
	2 PLACES ±0.25	±---
	1 PLACE ±---	±---
	ANGULAR ± 5 °	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
MLONG	2004/03/25
CHECKED BY	DATE
SRRAMESH	2004/03/26
APPROVED BY	DATE
GGLEE	2004/03/26
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	☉
TITLE		
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
MOLEX INCORPORATED		SHEET NO.
DOCUMENT NO. SD-87803-010		3 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		